

SOT528-1

plastic rectangular-DIL-bent-SIL power package; 13 leads

8 February 2016

Package information

1. Package summary

Terminal position code	Z (zig-zag)
Package type descriptive code	RDBS13P
Package type industry code	RDBS13P
Package style descriptive code	RDBS (right-angle DIL-bent-SIL)
Package style suffix code	P (power)
Package body material type	P (plastic)
Mounting method type	T (through-hole mount)
Issue date	12-3-2003

Table 1. Package summary

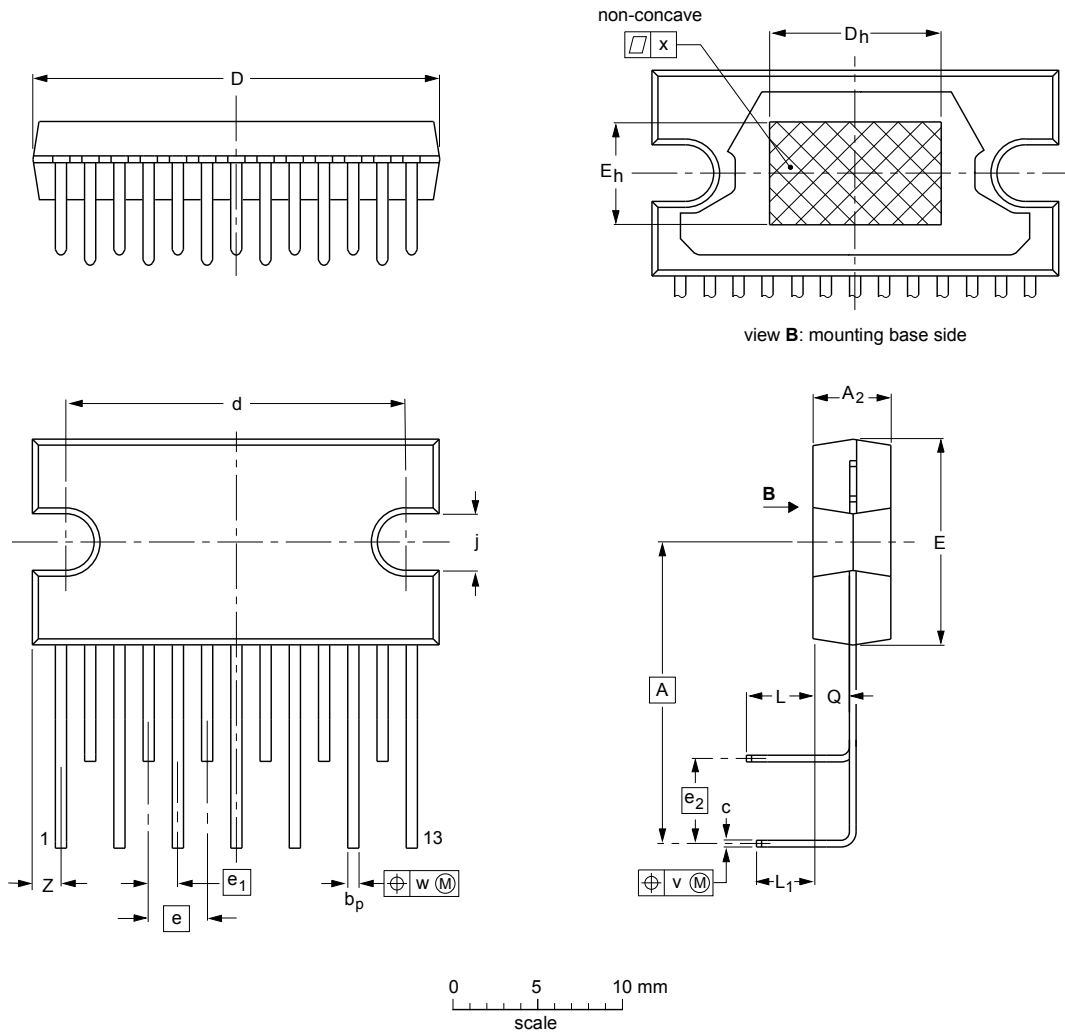
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	23.6	-	23.8	24	mm
E	package width	11.8	-	12	12.2	mm
A	seated height	[tbd]	-	17.7	[tbd]	mm
A ₂	package height	4.4	-	4.5	4.6	mm
n ₂	actual quantity of termination	-	-	13	-	



2. Package outline

RDBS13P: plastic rectangular-DIL-bent-SIL power package; 13 leads

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DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₂	b _p	c	D ⁽¹⁾	d	D _h	E ⁽¹⁾	e	e ₁	e ₂	E _h	j	L	L ₁	Q	v	w	x	Z ⁽¹⁾
mm	17.7	4.6 4.4	0.75 0.60	0.48 0.38	24.0 23.6	20.0 19.6	10	12.2 11.8	3.4	1.7	5.08	6	3.4 3.1	4.25 3.75	3.65 3.15	2.1 1.8	0.6	0.4	0.03	2.00 1.45

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT528-1						00-03-29 03-03-12

Fig. 1. Package outline RDBS13P (SOT528-1)

3. Legal information

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